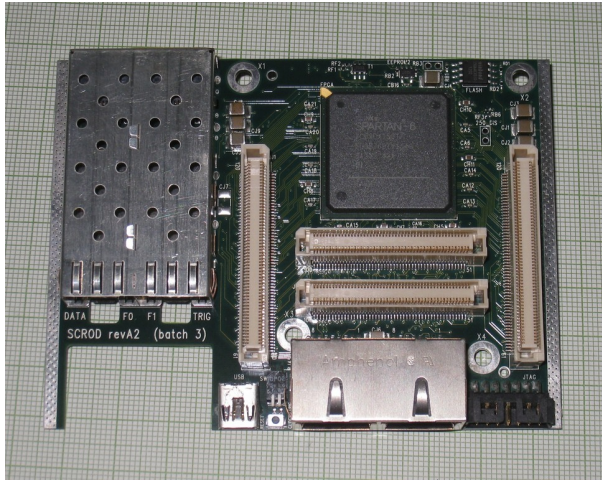
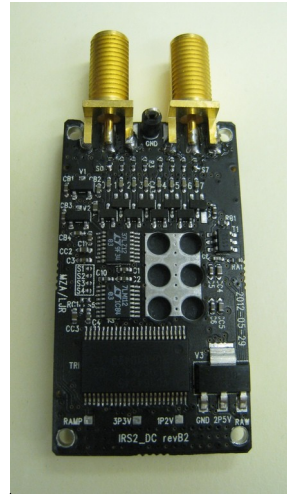


current status

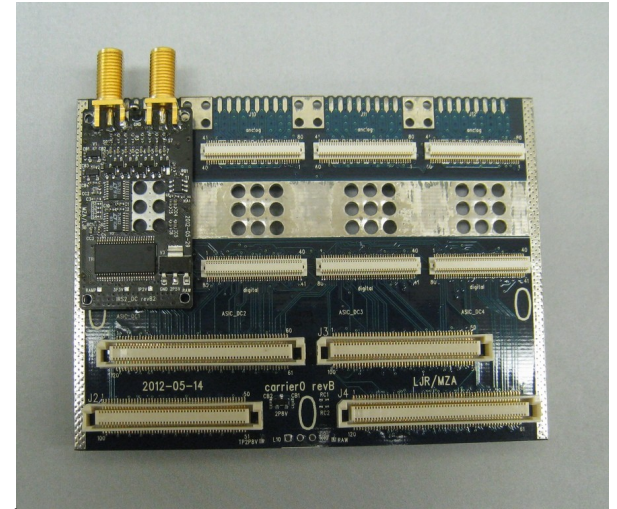
new PCB designs



SCROD revA2



IRS2_DC revB2



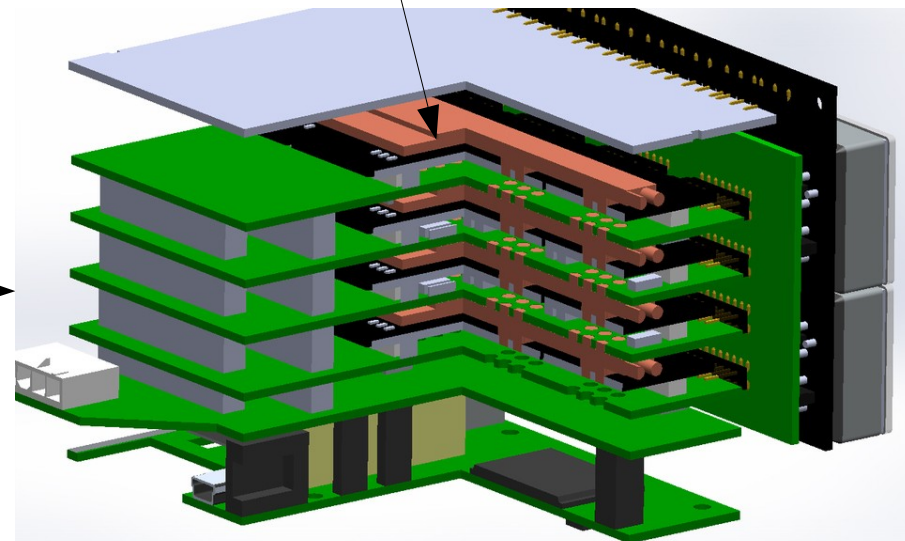
carrier0 revB

bench testing

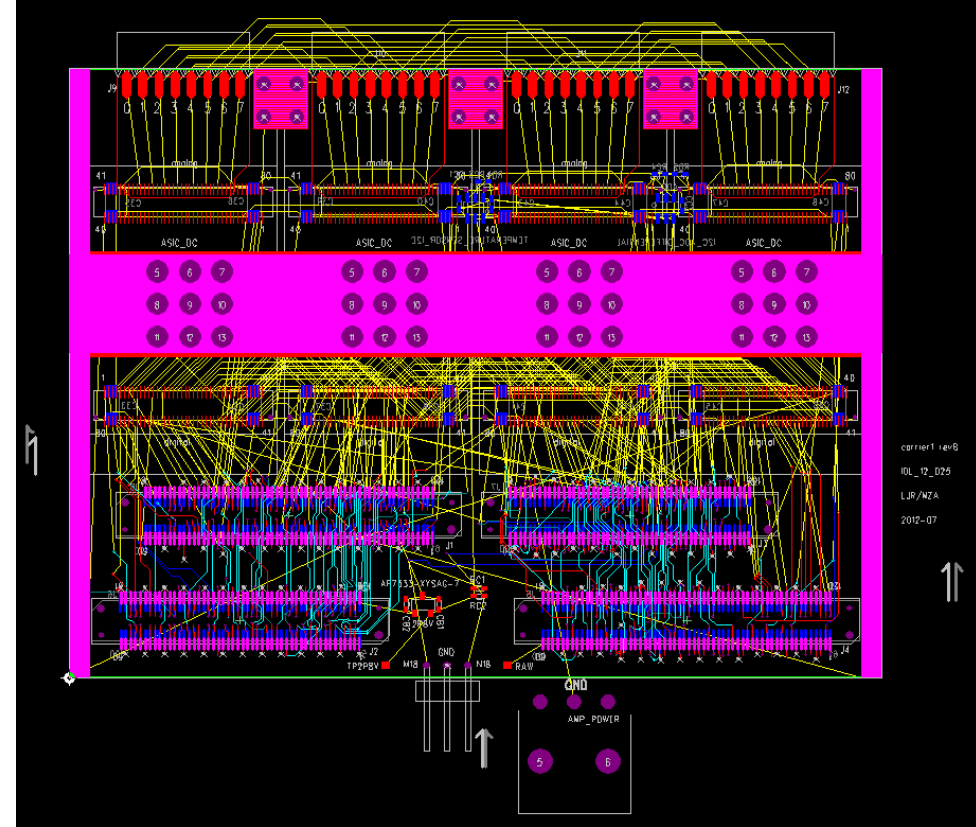


still too hot!

new heatsink concept



next steps



- design new carrier1,2,3
 - with new thermal structures for heatsinks
 - with different amplifier options
- new HV circuit idea being developed at Indiana
 - using high-voltage bipolar transistors
- rethink front-back, front-front boards
 - to eliminate 2mm connectors between boards